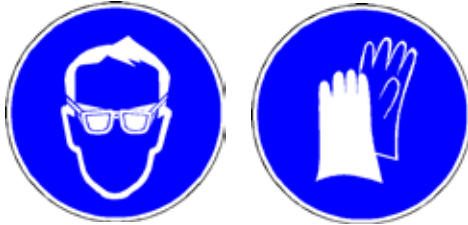


Processing Instructions for Biresin[®] Power Adhesive Thix

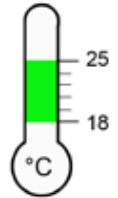
Necessary safety measures



Working conditions

Recommended temperature for:

- working environment
- board material
- and adhesive



* lower temperatures lead to an increase, higher temperatures to a decrease in the curing time

Preparation of the board material / the bonding areas

- Pre-roughening of the bonding areas is recommended (max. grain 80)
- Remove the dust with compressed air, or draw it off
- Clean with Sika Reinigungsmittel 5 or acetone and allow to evaporate
- Requirement: plane parallelism

Processing of the adhesive

- Mixing up the resin component
- Homogenize the mixture thoroughly (Mixing ratio = 100 : 33!)
- Application with a brush or a toothed spatula on both sides (potlife 30 min)
- Fix the bonding with sufficient clamps or a press
workable after approx. 16 h

Further information available at:

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